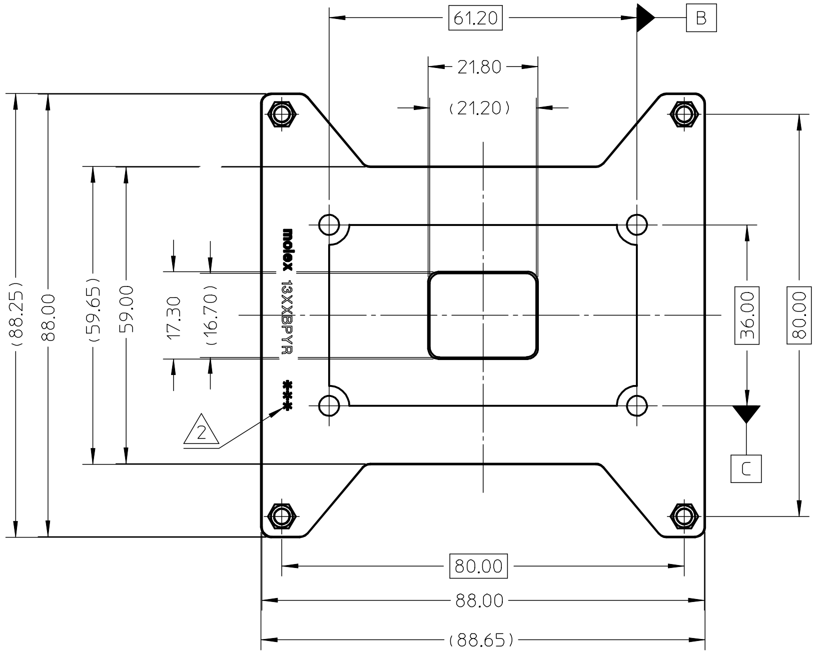
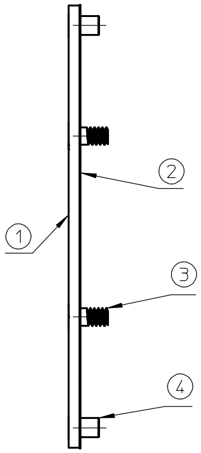
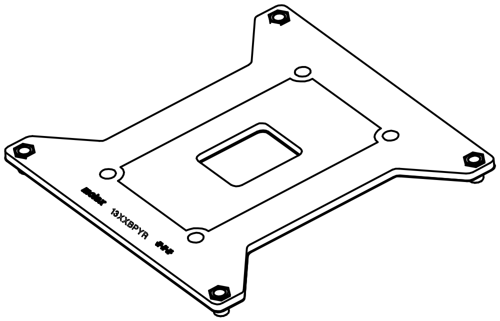
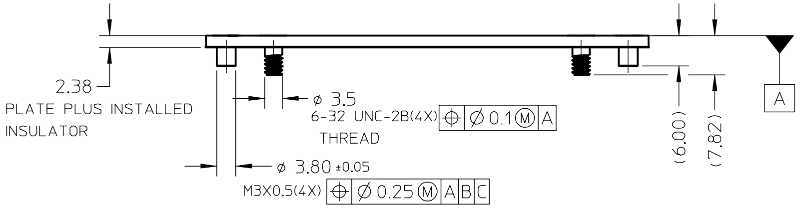






NOTES:

1. MATE WITH LGA13XX ILM ASSEMBLY DETAIL REFER TO SD-47593-900
2. DATE CODE
3. THE PARTS 475937000 COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC



BILL OF MATERIAL

ITEM NO	QTY	DESCRIPTION	MATERIAL
	1	BACK PLATE ASSEMBLY FOR SERVER	
①	1	BACK PLATE	STEEL WITH NICKEL PLATING
②	1	BACK PLATE INSULATOR	FORMEX GK-5BK
③	4	BACK PLATE SCREW	STEEL WITH NICKEL PLATING
④	4	BACK PLATE NUT	STEEL

ENTER DESCRIPTION
EC NO: SH2013-0064
DRWN:YXZHENG 2012/10/11
CH'KD:
APPR:AYIN 2013/02/04
DESCRIPTION
D
REV

QUALITY SYMBOLS
F_A=0
F_C=0
F_P=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.2	± ---
1 PLACE	± 0.3	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY YQSUN	DATE 2008/10/13	TITLE 13XX CKT SOCKET BACK PLATE ASSEMBLY FOR SERVER APPLICATION	
CHECKED BY JKACHLIC	DATE 2008/10/13		
APPROVED BY AYIN	DATE 2010/10/22	molex MOLEX INCORPORATED	
MATERIAL NO. 47593-7000		DOCUMENT NO. SD-47593-700	SHEET NO. 1 OF 1
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

NOTES:

1. MATERIAL:
   - HOUSING: LCP,UL94V-0,COLOR:BLACK.
   - TERMINAL:COPPER ALLOY.
   - PICK AND PLACE COVER:LCP.
   - SOLDER BALL:SEE THE TABLE.
2. PLATING:
   - SEE TABLE FOR GOLD ON CONTACT AREA.
   - 1.27 MICROMETER NICKEL UNDERPLATE.

△3. DATE-CODE LOCATION. AND DATE-CODE "YMDLS"
IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)

△4. PRODUCT NAME TO BE INDICATED IN THIS AREA.

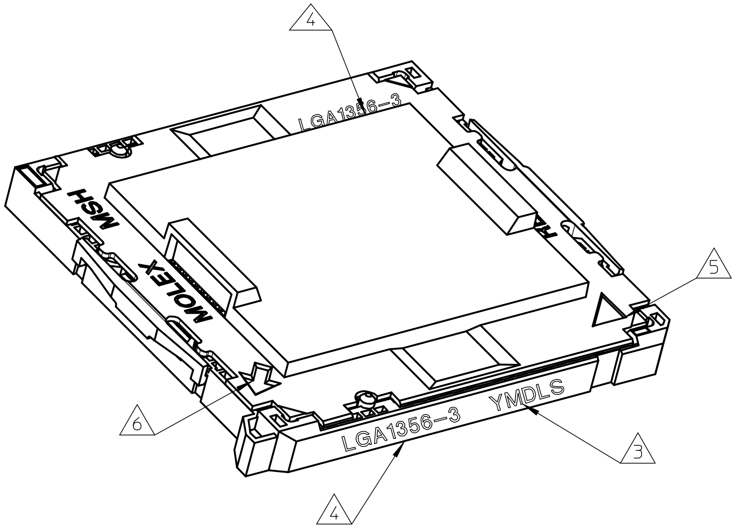
△5. SOCKET PIN 1 INDICATOR.

△6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.

8. PRODUCT PACKAGE PK-47594-003 APPLIES.

9. THE PARTS 47594*001/*002 COMPLIANT TO RoHS
DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.



LGA1356 SOCKET PART NUMBER LIST					PART NAME
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT	
475942001	GENERAL	15u"(0.38um)	LEAD FREE	YES	LGA1356-3(B3)
475942002	GENERAL	30u"(0.76um)			

REV	DESCRIPTION
1	**NEW RELEASED** EC NO: SH2013-0064 DRWN:YXZHENG 2012/09/24 CH'KD: APPR:AYIN 2013/02/04

QUALITY SYMBOLS

∇_{F_A}=0

∇_{F_C}=0

∇_{F_P}=0

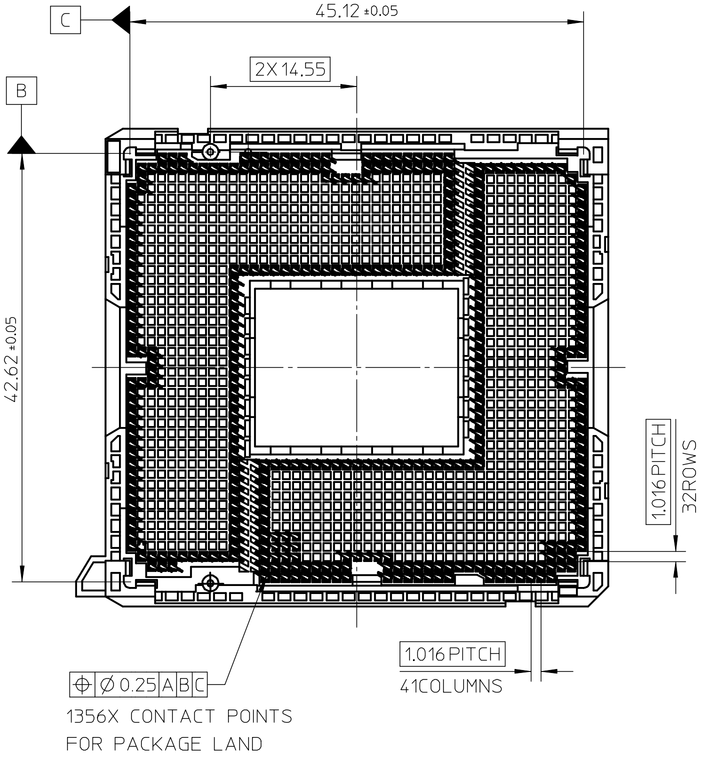
GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.25	± ---
0 PLACE	± ---	± ---
ANGULAR ± 1 °		

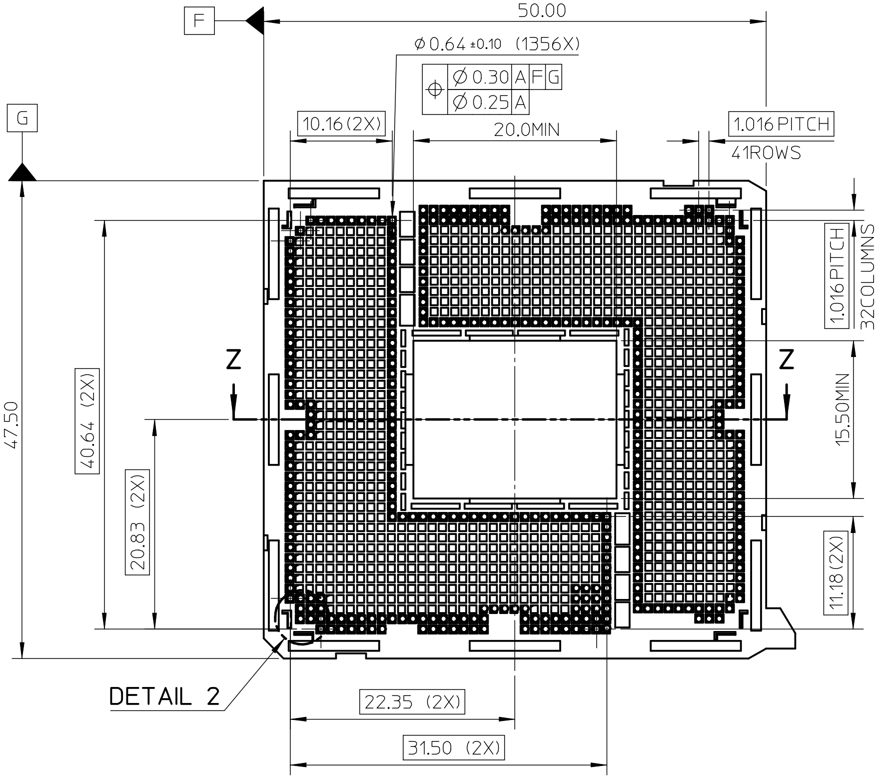
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

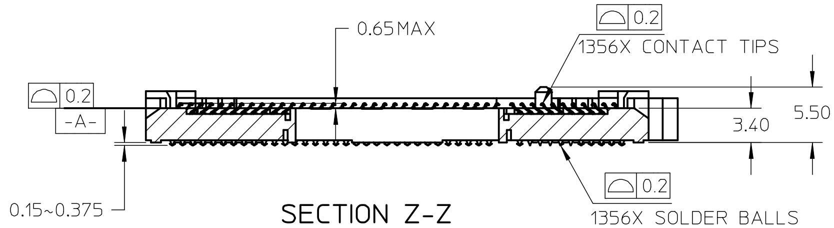
DIMENSION STYLE	SCALE	DESIGN UNITS	
MM ONLY	2:1	METRIC	THIRD ANGLE PROJECTION

DRAWN BY	DATE	TITLE
YXZHENG	2012/09/24	LGA1356-3 SOCKET(B3) FULL ASSEMBLY
CHECKED BY	DATE	
APPROVED BY	DATE	
AYIN	2013/02/04	**molex**
MATERIAL NO.		DOCUMENT NO. SD-47594-200
SEE TABLE		SHEET NO. 1 OF 3
SIZE A3		

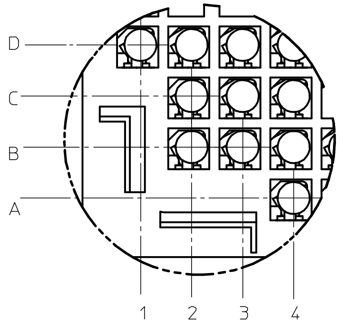
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION







SECTION Z-Z

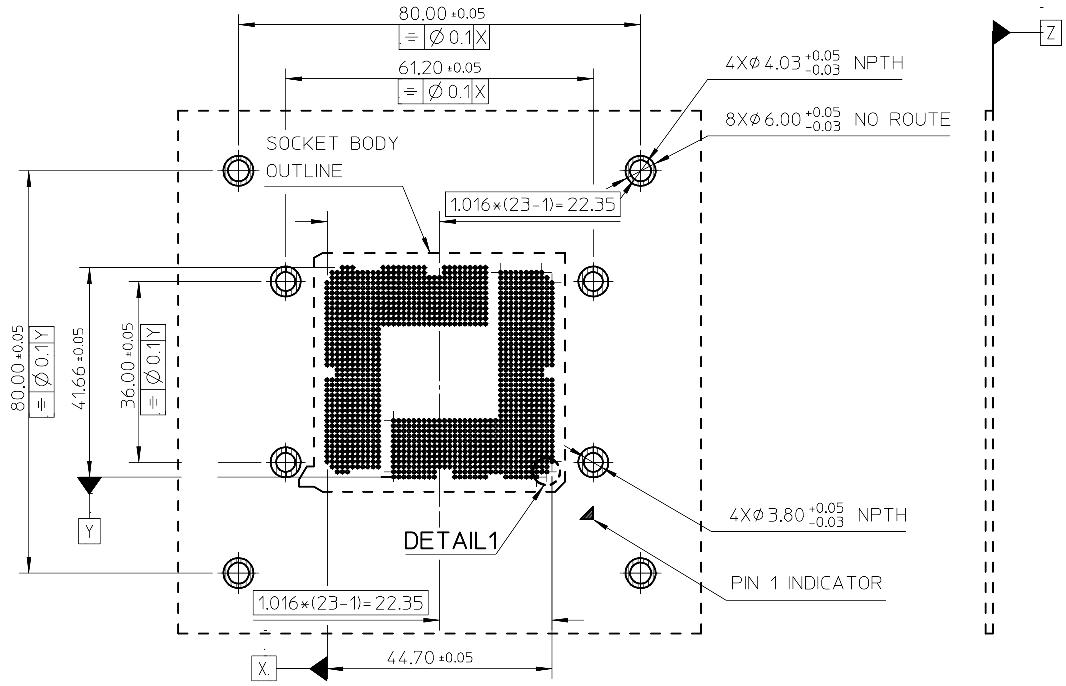


DETAIL2

QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		
		mm	INCH
F/A =0	4 PLACES	± ---	± ---
	3 PLACES	± ---	± ---
F/C =0	2 PLACES	± 0.20	± ---
	1 PLACE	± 0.25	± ---
F/P =0	0 PLACE	± ---	± ---
	ANGULAR ± 1 °		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

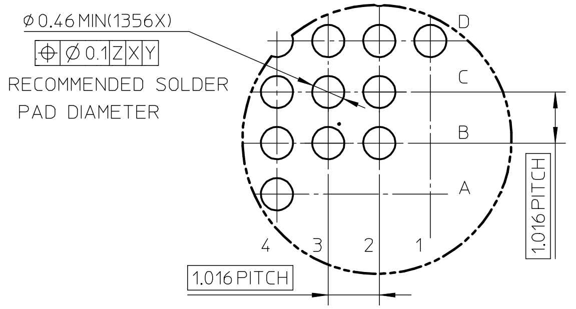
NEW RELEASED
EC NO: SH2013-0064 2012/09/24
DRWN:YXZHENG
CH'KD:
APPR:AYIN 2013/02/04
DESCRIPTION
1
REV

DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
DRAWN BY YXZHENG	DATE 2012/09/24	TITLE LGA1356-3 SOCKET(B3) FULL ASSEMBLY		
CHECKED BY	DATE			
APPROVED BY AYIN	DATE 2013/02/04	molex		
MATERIAL NO. SEE PAGE 1		DOCUMENT NO. SD-47594-200		SHEET NO. 2 OF 3
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



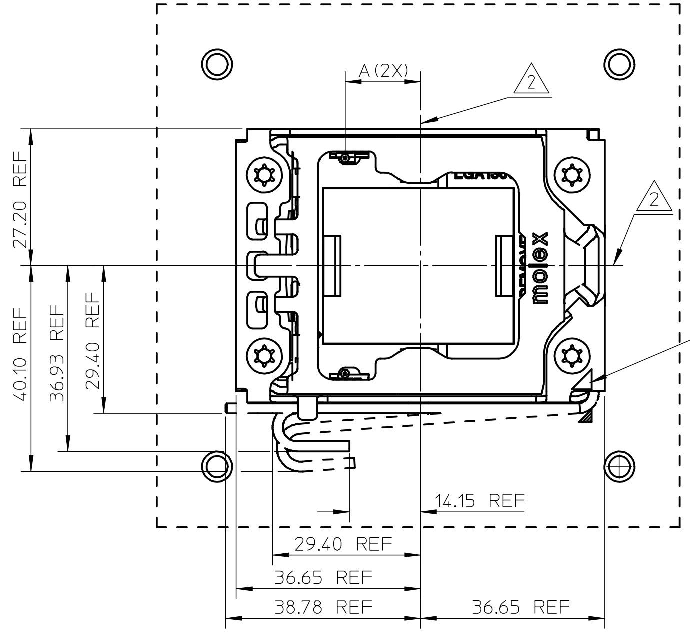
RECOMMEND PCB LAYOUT

THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



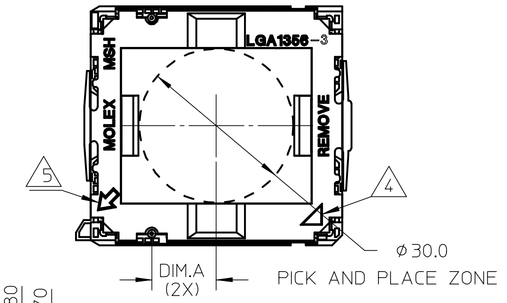
DETAIL1

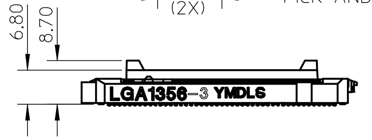
SCALE 10:1



SOCKET ON PCB(FOR REFERENCE ONLY)

LOAD PLATE IS NOT LOCKED





NOTES
1. DATUMN A IS THE PLANE WHICH SOCKET WILL BE SEATED.
2. GEOMETRIC CENTER OF CPU PACKAGE/SOCKET HOUSING CAVITY.
3. BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
4. SOCKET PIN 1 INDICATOR.
5. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
6. ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES;

REV	DESCRIPTION
1	NEW RELEASED EC NO: SH2013-0064 DRWN:YXZHENG 2012/09/24 CH'KD: APPR:AYIN 2013/02/04

QUALITY SYMBOLS
F/A =0
F/C =0
F/P =0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.25	± ---
0 PLACE	± ---	± ---

ANGULAR ± 1 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS	
MM ONLY	1:1	METRIC	THIRD ANGLE PROJECTION

DRAWN BY	DATE	TITLE
YXZHENG	2012/09/24	LGA1356-3 SOCKET(B3) FULL ASSEMBLY
CHECKED BY	DATE	
APPROVED BY	DATE	molex
AYIN	2013/02/04	
MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE PAGE 1	SD-47594-200	3 OF 3

SIZE A3